

Docket No.: JCLA8534-D

Date: December 03, 2003

COMMISSIONER FOR PATENTS
P.O. BOX 1450
ALEXANDRIA, VA 22313-1450

ATTENTION: APPLICATION BRANCH

Sir:

This is a request for filing a continuation application under 37 CFR 1.53 (b) as a **divisional application** of prior application No. 10/055,499 filed on **January 22, 2002**.

Prior application information: **Examiner: THAI, LUAN C. ; Group Art Unit: 2827**

The entire disclosure of the prior application, from which an oath or declaration is supplied herewith as indicated below, is considered a part of the disclosure of the accompanying continuation or divisional application and is hereby incorporated by reference.

Transmitted herewith for filing is the patent application of

Inventor(s): JIN-YUAN LEE ;
MOU-SHIUNG LIN ;
CHING-CHENG HUANG ;

For: INTEGRATED CHIP PACKAGE STRUCTURE USING ORGANIC SUBSTRATE AND METHOD OF MANUFACTURING THE SAME

Enclosed are:

- (X) Specification in SIXTY-SIX (66) pages.
- (X) SEVENTEEN (17) sheets of Drawings.
- (X) Preliminary Amendment.
- (X) A copy of Declaration and Power of Attorney from the prior application is enclosed.
- (X) **Applicant claims small entity status. See 37 CFR 1.27.**
- (X) Return prepaid postcard.

CLAIMS AS FILED				
FOR	NUMBER FILED	NUMBER EXTRA	RATE	FEE
Basic Fee			\$ 385	\$ 385
Total Claims	88 - 20 =	68 ×	\$ 9	\$ 612
Independent Claims	3 - 3 =	0 ×	\$ 43	\$ 0
If application contains any multiple dependent claims(s), then add			\$ 145	\$ 0
For a Small Entity:	TOTAL FILING FEE			\$ 997

- (X) A check in the amount of \$ 997 to cover the filing fee is enclosed.
- (X) The commissioner is authorized to charge any additional necessary fee to Account No. 50-0710 (Order No. JCLA8534-D). A duplicate copy of this sheet is enclosed.

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17510 U.S. PTO
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CERTIFICATE OF MAILING BY "EXPRESS MAIL"

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Inventor(s) : JIN-YUAN LEE ;
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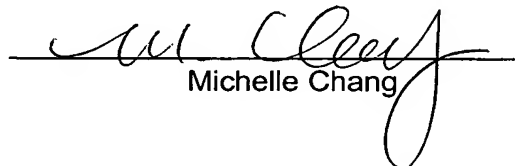
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Date of Deposit : December 03, 2003

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application; Preliminary Amendment; Checks for Filing Fee(s); Return
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are being deposited with the United States Postal Service "Express Mail Post Office to
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addressed to the Commissioner for Patents, P.O. BOX 1450, Alexandria, VA 22313-
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Michelle Chang